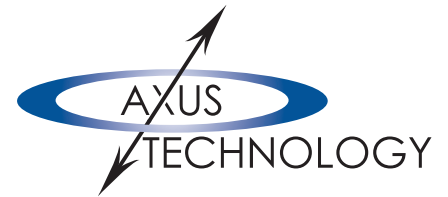


OnTrak DSS 200 Series 1



Your source for leading-edge surface processing solutions



STD FEATURES

- Universal load station
- Double sided PVA scrub
- Dual brush boxes
- Ammonia dispense
- IR assisted spin dry station
- Robotic unload
- Vertical unload station
- Touchscreen controls

OnTrak DSS 200 Series 1 double-sided PVA scrubber is designed to clean 100mm to 200mm wafers. It provides consistent, ultra-clean processing for a wide variety of applications.

The DSS-200 Series 1 is a proven, cost-effective cleaning system for the following applications :

- Post-CMP Cleaning: oxide, polysilicon, nitride, tungsten, aluminum and copper
- General purpose cleaning: post-CVD oxides, post-metallization, surface topography cleaning, trench cleaning
- Silicon cleaning: prime silicon, reclaim silicon, fab monitor reclaim



OnTrak DSS 200 Series 1

FEATURES	BENEFITS
DSS-200 Megasonic Option Megasonic transducer mounted on SRD rinse nozzle perpendicular to the wafer surface. High-Frequency system (1-2 MHz) that generates acoustic waves and controlled cavitation providing an enhanced cleaning method while protecting the wafer	Provides an additional cleaning for removing larger surface particles using a non-contact method.
Pressure Vessel for Chemical Distribution 16-gallon (60-liter) capacity Configured with tubing and connectors needed to interface with the chemical system inputs	Fully configured for chemical mixing and easy set up in your fab
Chemical Delivery Upgrade – Single Chemistry Features Through-The-Brush chemical delivery Assembly, Kit, Single Chemistry system	Provides much better and more consistent cleaning results by evenly distributing the cleaning chemistries in the brush. In addition, the constant flow of chemistry and water prevents brush loading.
Chemical Delivery Upgrade – Dual Chemistry Features Through-The-Brush chemical delivery Assembly, Kit, Dual Chemistry system	Enables two cleaning chemistries through the brush modules for maximum production flexibility and provides much better and more consistent cleaning results by evenly distributing the cleaning chemistries in the brush. In addition, the constant flow of chemistry and water prevents brush loading.
Idle D.I. H₂O Conservation/Use Reduction System Upgrade A recirculation and filtration system developed by AT that allows for the use of a fixed amount of DI water for a selected period to significantly reduce the use of DI water during idle time.	Significantly reduces the use of DI water during idle time.
Crystal Grip DSS200 Ontrak cleaner upgrade for handling ultra-thin wafers 300µm and below	Enables sub 300µm thickness wafer handling and fragile wafers without breakage.
Transparent Wafer Sensor Kit 200mm Kit provides specialized sensors to be able to detect clear or semi-clear wafers	Enables reliable detection of 200mm clear glass wafers in a wet environment.
Transparent Wafer Sensor Kit 100mm to 150mm Kit provides specialized sensors to be able to detect clear or semi-clear wafers with flat finder	Enables reliable detection of 100mm and 150mm clear glass wafers in a wet environment.
True Touch Closed Loop Brush-Gap Control System Programmable brush gap and brush motor feedback for the most accurate brush pressure	Monitors brush motor current in a closed loop feedback to adjust brush gap to maintain continuous process control resulting in less manual adjusting and improved constant cleaning results.